

Datasheet revision 1.0

Chip Quik Removal Alloy (8ft. In 15-6.5in. Lengths) lead-free

Product Highlights

Easily remove SMD parts with Chip Quik® removal alloy Reduce heat and reduce damage to circuit boards and SMD parts during removal Use with SMD291 flux RoHS II and REACH compliant

Specifications

Alloy: Melting Point: Chip Quik® lead-free 79-91°C (174-195°F)

Chip Quik® Instructions		
	1	Apply Chip Quik flux to all leads of SMD with syringe or flux applicator.
	2	Melt Chip Quik low temperature alloy uniformly on all pins of SMD. Maintain alloy in molten state long enough for complete reflow.
	3	Lift chip from board with dental pick or vacuum pen.
	4	Thoroughly clean site with swab dipped in flux while applying heat. Clean thoroughly with alcohol pad.

SMD Removal

(With solder iron or warm air bath)

- Apply flux to all leads.
- Melt CHIP QUIK® uniformly on all pins.
- Maintain alloy in molten state long enough to release chip.
- Lift chip from board with dental pick or vacuum pen.

CLEAN UP

- While molten, use cotton swab and flux to move excess to an unused section of board.
- While applying heat, polish each pad with a swab and flux until thoroughly clean.
- At room temperature, clean residue with alcohol pad.
- You are now ready to install the new chip.

2.5 ft of Chip Quik® material, removes 1250 to 1500 SMD pins.

Conforms to the following Industry Standards: J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 2 Directive 2011/65/EU: Yes